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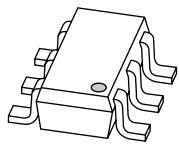
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Kind regards,

Team Nexperia



PBSS4420D

20 V, 4 A NPN low V_{CEsat} (BISS) transistor

Rev. 02 — 24 September 2008

Product data sheet

1. Product profile

1.1 General description

NPN low V_{CEsat} Breakthrough in Small Signal (BISS) transistor in a small SOT457 (SC-74) Surface-Mounted Device (SMD) plastic package.

PNP complement: PBSS5420D.

1.2 Features

- Very low collector-emitter saturation resistance
- Ultra low collector-emitter saturation voltage
- 4 A continuous collector current
- Up to 15 A peak current
- High efficiency due to less heat generation

1.3 Applications

- Power management functions
- Charging circuits
- DC-to-DC conversion
- MOSFET gate driving
- Power switches (e.g. motors, fans)
- Thin Film Transistor (TFT) backlight inverter

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
V_{CEO}	collector-emitter voltage	open base	-	-	20	V	
I_C	collector current		[1]	-	4	A	
I_{CM}	peak collector current	single pulse; $t_p \leq 1$ ms	-	-	15	A	
R_{CEsat}	collector-emitter saturation resistance	$I_C = 4$ A; $I_B = 400$ mA	[2]	-	50	70	$m\Omega$

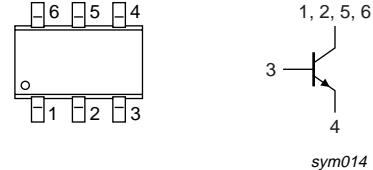
[1] Device mounted on a ceramic Printed-Circuit Board (PCB), Al_2O_3 , standard footprint.

[2] Pulse test: $t_p \leq 300$ μ s; $\delta \leq 0.02$.

2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	collector		
2	collector		
3	base		
4	emitter		
5	collector		
6	collector		



sym014

3. Ordering information

Table 3. Ordering information

Type number	Package			Version
	Name	Description		
PBSS4420D	SC-74	plastic surface-mounted package (TSOP6); 6 leads		SOT457

4. Marking

Table 4. Marking codes

Type number	Marking code
PBSS4420D	D4

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CBO}	collector-base voltage	open emitter	-	20	V
V_{CEO}	collector-emitter voltage	open base	-	20	V
V_{EBO}	emitter-base voltage	open collector	-	5	V
I_C	collector current		[1]	-	A
I_{CM}	peak collector current	single pulse; $t_p \leq 1 \text{ ms}$	-	15	A
I_B	base current		-	0.8	A
I_{BM}	peak base current	single pulse; $t_p \leq 1 \text{ ms}$	-	2	A
P_{tot}	total power dissipation	$T_{amb} \leq 25^\circ\text{C}$	[2]	-	mW
			[3]	-	mW
			[4]	-	mW
			[1]	-	W
			[2][5]	-	W

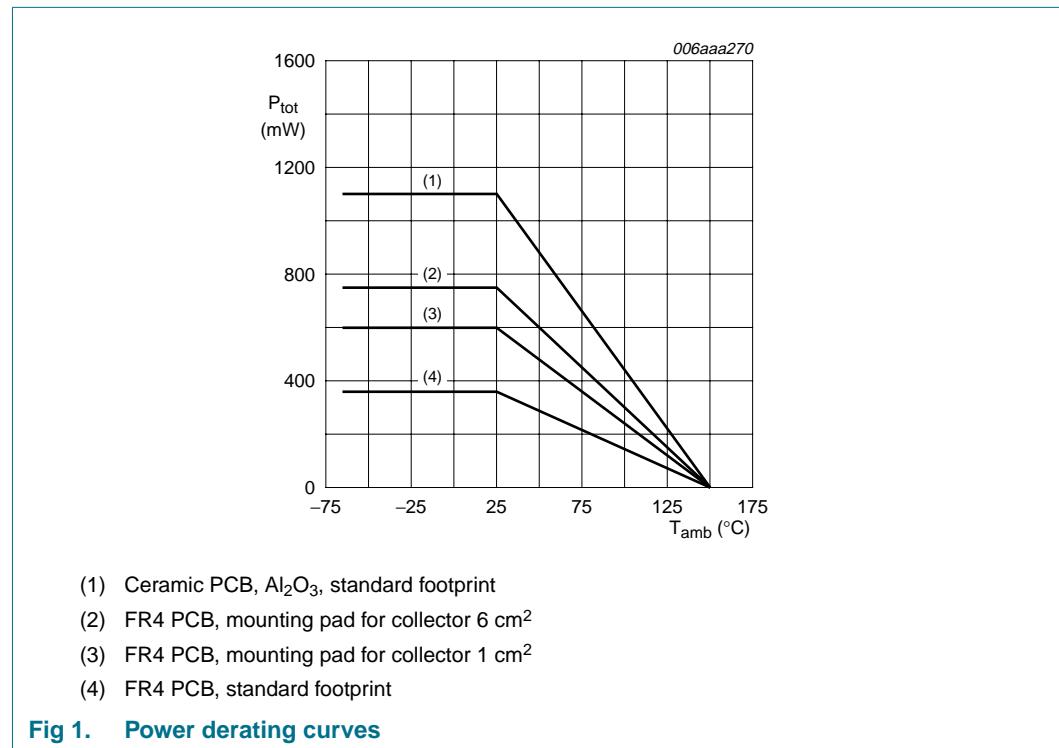
Table 5. Limiting values ...continued

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
T_j	junction temperature		-	150	°C
T_{amb}	ambient temperature		-65	+150	°C
T_{stg}	storage temperature		-65	+150	°C

[1] Device mounted on a ceramic PCB, Al_2O_3 , standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

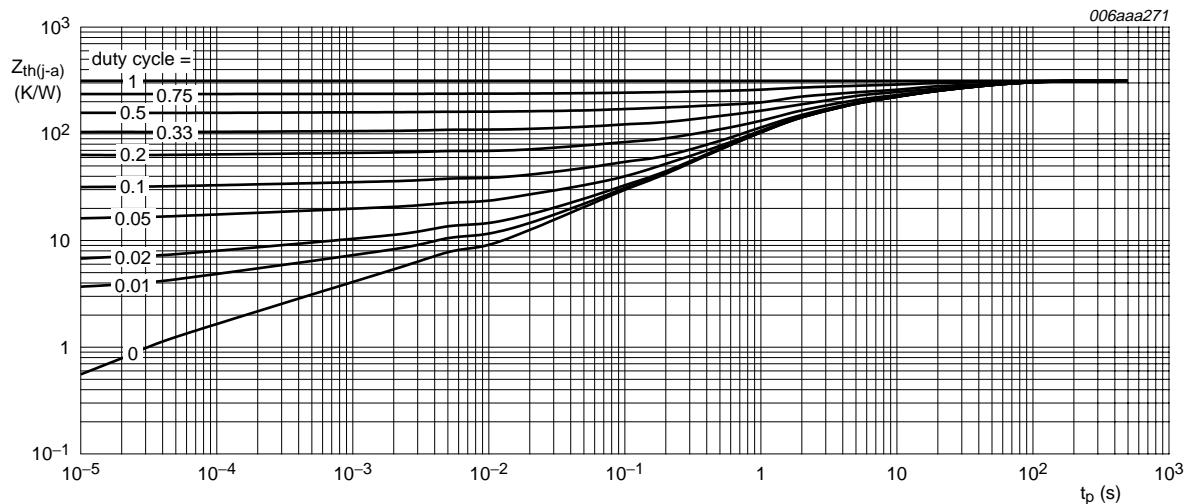
[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm^2 .[4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm^2 .[5] Operated under pulsed conditions: Duty cycle $\delta \leq 10\%$ and pulse width $t_p \leq 10\text{ ms}$.

6. Thermal characteristics

Table 6. Thermal characteristics

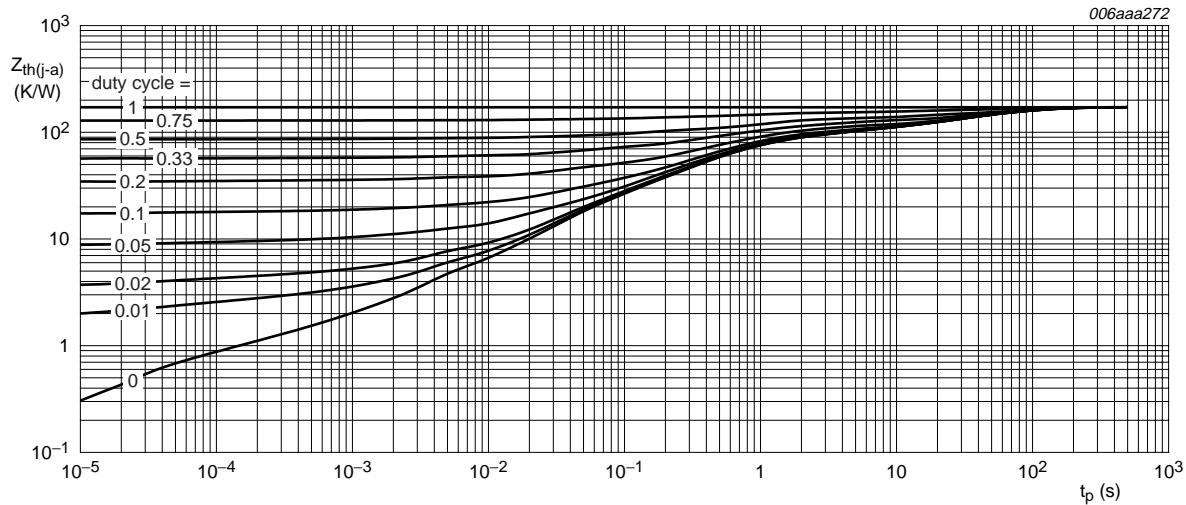
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	-	350 K/W
			[2]	-	-	208 K/W
			[3]	-	-	160 K/W
			[4]	-	-	113 K/W
			[1][5]	-	-	50 K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		-	-	45	K/W

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm².
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm².
- [4] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.
- [5] Operated under pulsed conditions: Duty cycle $\delta \leq 10\%$ and pulse width $t_p \leq 10$ ms.



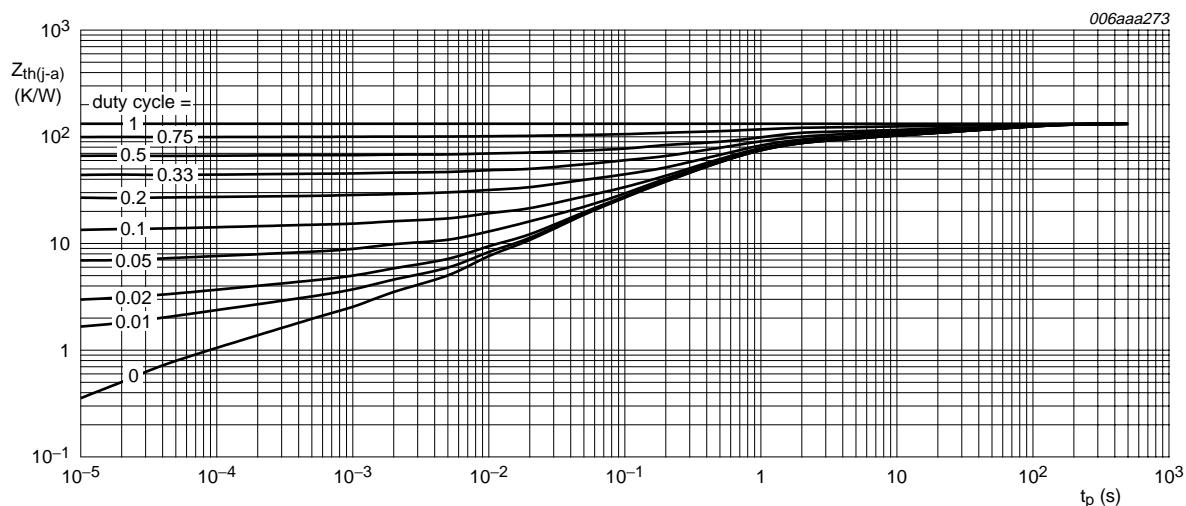
FR4 PCB, standard footprint

Fig 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for collector 1 cm^2

Fig 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for collector 6 cm^2

Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

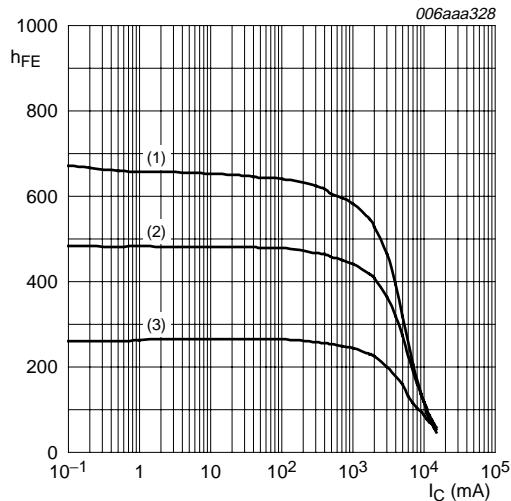
7. Characteristics

Table 7. Characteristics

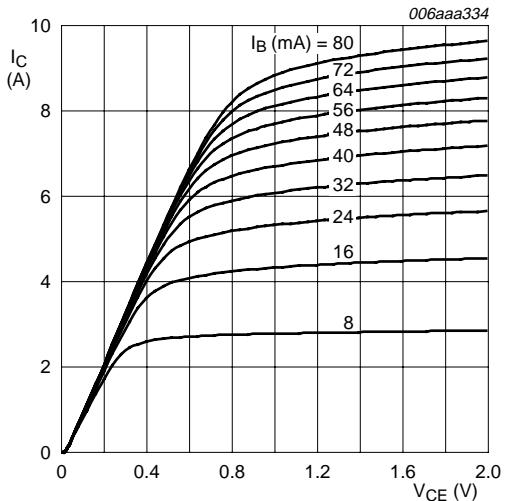
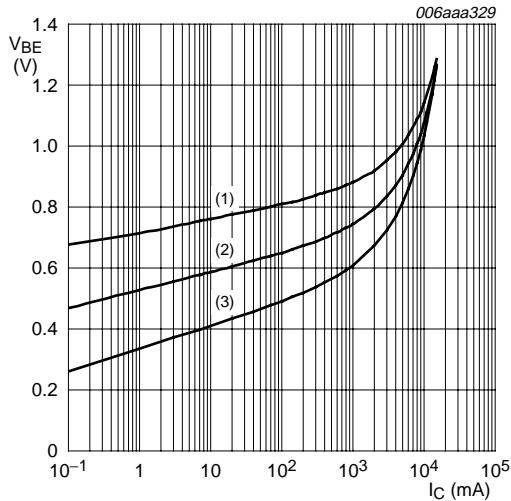
$T_{amb} = 25^\circ C$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_{CBO}	collector-base cut-off current	$V_{CB} = 20 \text{ V}; I_E = 0 \text{ A}$	-	-	0.1	μA
		$V_{CB} = 20 \text{ V}; I_E = 0 \text{ A}; T_j = 150^\circ \text{C}$	-	-	50	μA
I_{CES}	collector-emitter cut-off current	$V_{CE} = 20 \text{ V}; V_{BE} = 0 \text{ V}$	-	-	0.1	μA
I_{EBO}	emitter-base cut-off current	$V_{EB} = 5 \text{ V}; I_C = 0 \text{ A}$	-	-	0.1	μA
h_{FE}	DC current gain	$V_{CE} = 2 \text{ V}; I_C = 0.5 \text{ A}$	300	450	-	
		$V_{CE} = 2 \text{ V}; I_C = 1 \text{ A}$	[1]	300	430	-
		$V_{CE} = 2 \text{ V}; I_C = 2 \text{ A}$	[1]	250	400	-
		$V_{CE} = 2 \text{ V}; I_C = 4 \text{ A}$	[1]	200	310	-
		$V_{CE} = 2 \text{ V}; I_C = 6 \text{ A}$	[1]	100	230	-
V_{CEsat}	collector-emitter saturation voltage	$I_C = 0.5 \text{ A}; I_B = 50 \text{ mA}$	-	30	50	mV
		$I_C = 1 \text{ A}; I_B = 50 \text{ mA}$	-	60	90	mV
		$I_C = 2 \text{ A}; I_B = 200 \text{ mA}$	-	110	150	mV
		$I_C = 4 \text{ A}; I_B = 400 \text{ mA}$	[1]	-	200	mV
		$I_C = 6 \text{ A}; I_B = 600 \text{ mA}$	[1]	-	300	mV
R_{CEsat}	collector-emitter saturation resistance	$I_C = 4 \text{ A}; I_B = 400 \text{ mA}$	[1]	-	50	$\text{m}\Omega$
V_{BEsat}	base-emitter saturation voltage	$I_C = 0.5 \text{ A}; I_B = 50 \text{ mA}$	-	0.79	0.85	V
		$I_C = 1 \text{ A}; I_B = 50 \text{ mA}$	-	0.81	0.9	V
		$I_C = 1 \text{ A}; I_B = 100 \text{ mA}$	[1]	-	0.83	V
		$I_C = 4 \text{ A}; I_B = 400 \text{ mA}$	[1]	-	1.0	1.1 V
V_{BEon}	base-emitter turn-on voltage	$V_{CE} = 2 \text{ V}; I_C = 2 \text{ A}$	-	0.79	1	V
t_d	delay time	$V_{CC} = 12.5 \text{ V}; I_C = 3 \text{ A}; I_{Bon} = 0.15 \text{ A}; I_{Boff} = -0.15 \text{ A}$	-	12	-	ns
t_r	rise time		-	36	-	ns
t_{on}	turn-on time		-	48	-	ns
t_s	storage time		-	230	-	ns
t_f	fall time		-	50	-	ns
t_{off}	turn-off time		-	280	-	ns
f_T	transition frequency	$V_{CE} = 10 \text{ V}; I_C = 0.1 \text{ A}; f = 100 \text{ MHz}$	-	100	-	MHz
C_c	collector capacitance	$V_{CB} = 10 \text{ V}; I_E = i_e = 0 \text{ A}; f = 1 \text{ MHz}$	-	60	-	pF

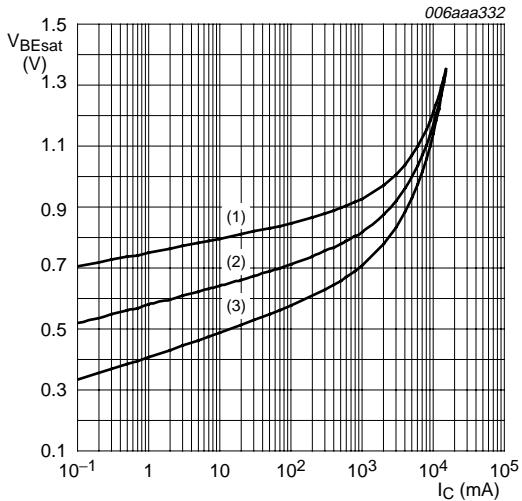
[1] Pulse test: $t_p \leq 300 \mu\text{s}; \delta \leq 0.02$.

 $V_{CE} = 2\text{ V}$

- (1) $T_{amb} = 100\text{ }^{\circ}\text{C}$
- (2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
- (3) $T_{amb} = -55\text{ }^{\circ}\text{C}$

Fig 5. DC current gain as a function of collector current; typical values $T_{amb} = 25\text{ }^{\circ}\text{C}$ **Fig 6.** Collector current as a function of collector-emitter voltage; typical values $V_{CE} = 2\text{ V}$

- (1) $T_{amb} = -55\text{ }^{\circ}\text{C}$
- (2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
- (3) $T_{amb} = 100\text{ }^{\circ}\text{C}$

Fig 7. Base-emitter voltage as a function of collector current; typical values $I_C/I_B = 20$ **Fig 8.** Base-emitter saturation voltage as a function of collector current; typical values

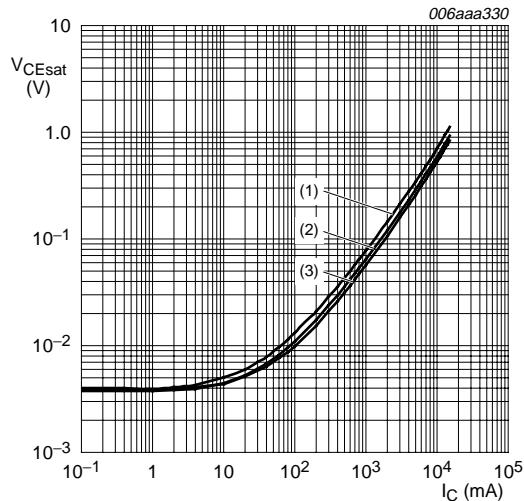


Fig 9. Collector-emitter saturation voltage as a function of collector current; typical values

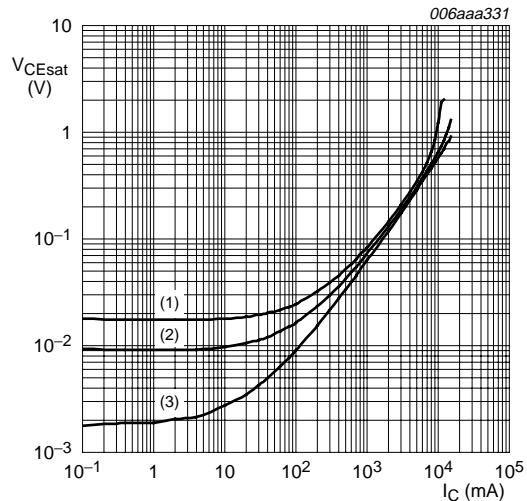


Fig 10. Collector-emitter saturation voltage as a function of collector current; typical values

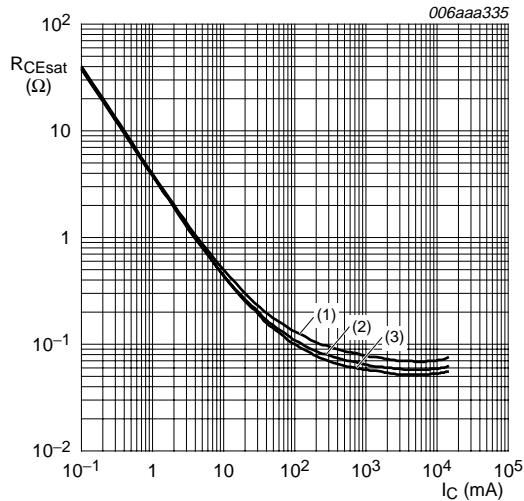


Fig 11. Collector-emitter saturation resistance as a function of collector current; typical values

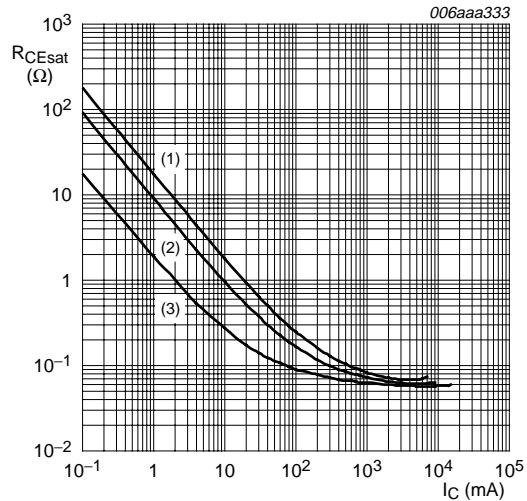


Fig 12. Collector-emitter saturation resistance as a function of collector current; typical values

8. Test information

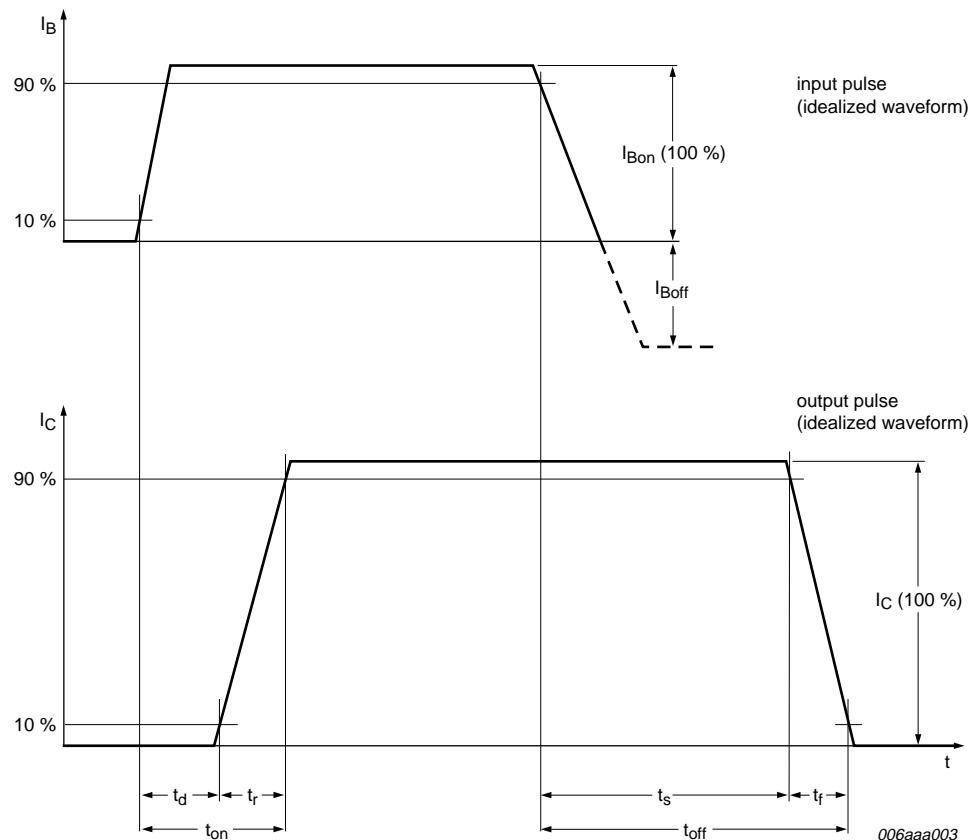
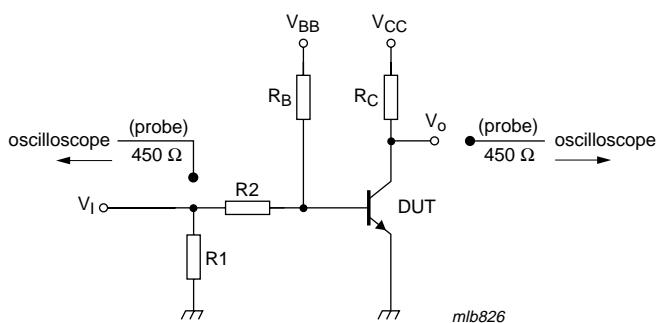


Fig 13. BISS transistor switching time definition



$V_{CC} = 12.5 \text{ V}$; $I_C = 3 \text{ A}$; $I_{B_{on}} = 0.15 \text{ A}$; $I_{B_{off}} = -0.15 \text{ A}$

Fig 14. Test circuit for switching times

9. Package outline

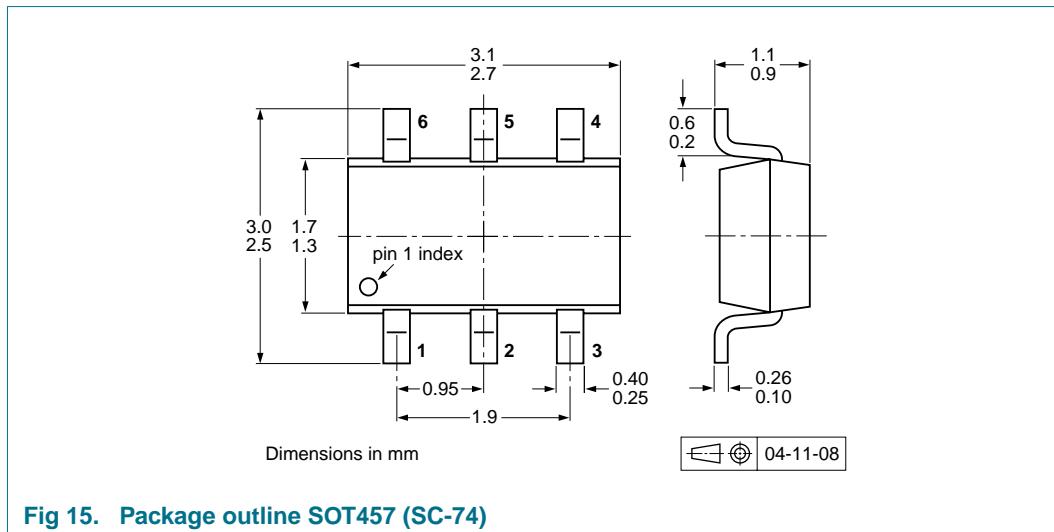


Fig 15. Package outline SOT457 (SC-74)

10. Packing information

Table 8. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

Type number	Package	Description	Packing quantity	
			3000	10000
PBSS4420D	SOT457	4 mm pitch, 8 mm tape and reel; T1	[2] -115	-135
		4 mm pitch, 8 mm tape and reel; T2	[3] -125	-165

[1] For further information and the availability of packing methods, see [Section 14](#).

[2] T1: normal taping

[3] T2: reverse taping

11. Soldering

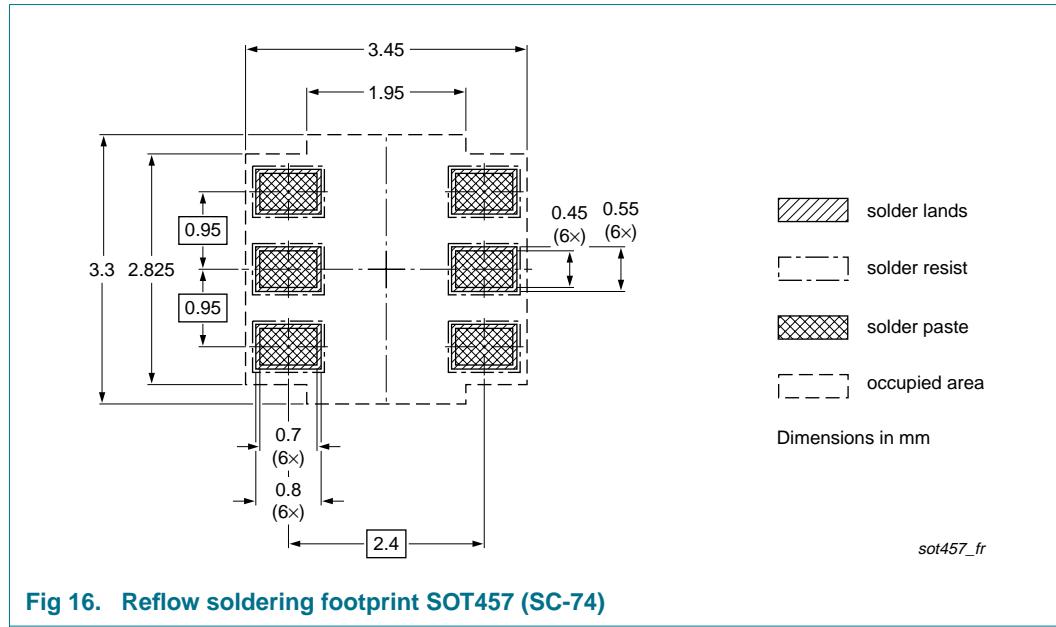


Fig 16. Reflow soldering footprint SOT457 (SC-74)

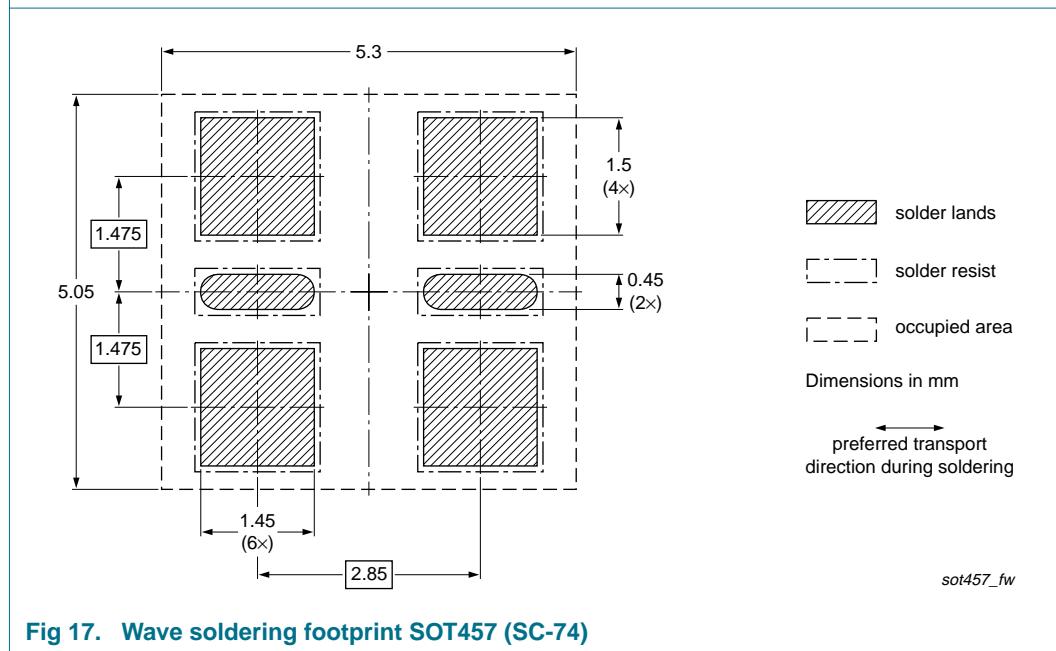


Fig 17. Wave soldering footprint SOT457 (SC-74)

12. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PBSS4420D_2	20080924	Product data sheet	-	PBSS4420D_1
Modifications:		<ul style="list-style-type: none">The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.Legal texts have been adapted to the new company name where appropriate.Figure 7: amendedSection 11 "Soldering": addedSection 13 "Legal information": updated		
PBSS4420D_1	20050421	Product data sheet	-	-

13. Legal information

13.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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15. Contents

1	Product profile	1
1.1	General description	1
1.2	Features	1
1.3	Applications	1
1.4	Quick reference data	1
2	Pinning information	2
3	Ordering information	2
4	Marking	2
5	Limiting values	2
6	Thermal characteristics	4
7	Characteristics	6
8	Test information	9
9	Package outline	10
10	Packing information	10
11	Soldering	11
12	Revision history	12
13	Legal information	13
13.1	Data sheet status	13
13.2	Definitions	13
13.3	Disclaimers	13
13.4	Trademarks	13
14	Contact information	13
15	Contents	14

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Date of release: 24 September 2008

Document identifier: PBSS4420D_2



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